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PEMTRON Highlights Advanced Wafer and 3D X-ray Inspection at SEMICON Korea

January 2026 — PEMTRON, an inspection equipment developer and supplier, will exhibit its latest semiconductor and electronics inspection technologies at SEMICON Korea 2026, taking place February 11–13 at COEX in Seoul. Visitors can find PEMTRON at Booth B1004, where the company will highlight the 8800WIR Wafer Inspection System, JUPITER 3D X-ray Inspection System, and MARS Automated Visual Inspection (AVI) System.

These systems reflect PEMTRON's continued focus on inspection solutions that support yield improvement, early defect detection, and process control across semiconductor and advanced packaging production.

8800WIR: Advanced Imaging for Wafer Defect Detection

The 8800WIR wafer inspection system combines advanced 2D and 3D imaging technologies to inspect a wide range of bump structures, including micro bumps. Designed to support early-stage defect detection, the system helps manufacturers identify quality issues before they impact downstream processes. By detecting even small and difficult-to-find defects, the 8800WIR supports improved yield and overall product quality in wafer-level manufacturing.

JUPITER: 3D X-ray Inspection for In-Line Process Insight

The JUPITER 3D X-ray Inspection System provides both 3D and 2D inspection using advanced PCT reconstruction-based processing. The system combines high-resolution optical imaging with PEMTRON's proven AOI defect detection algorithms, delivering detailed inspection results for in-line monitoring and process analysis. JUPITER also enables seamless data sharing with SPI and AOI systems, helping manufacturers gain better visibility into production trends and process stability.

MARS: High-Speed Inspection for Memory Module Production

The MARS Automated Visual Inspection (AVI) system is designed specifically for memory module manufacturing, where speed and consistency are critical. Using advanced image processing and high-speed inspection capabilities, MARS supports reliable detection of defects in high-volume production environments, helping manufacturers maintain throughput while meeting quality requirements.

Visit PEMTRON at SEMICON Korea 2026

Attendees are invited to visit Booth B1004 to learn more about PEMTRON’s inspection technologies and how they support wafer-level inspection, advanced packaging, and memory module production.

For more information about PEMTRON, please visit www.pemtron.com.

About PEMTRON

Based on 3D precision measurement and vision source technology, PEMTRON develops equipment used in various fields such as SMT, Automotive Field, Lead Tab, Semiconductor, and supplies Soldering Inspection equipment (3D SPI), 3D Mounting Inspection equipment (3D AOI, MOI), Conformal Coating Inspection equipment (TROI-8800 CI), Bottom Head Inspection equipment (Eagle 8800TH), Top & Bottom Double Sided Simultaneous Inspection equipment (Eagle 8800TWIN), Automated X-Ray SMD Counter (MERCURY), Wafer Sawing Before/After 3D Inspection equipment (8800 WI/WIR), Wire Bonding 3D Inspection & MEMS Auto Inspection equipment(ZEUS), Package AVI equipment (APOLLON), Memory Module / SSD Auto Inspection equipment (MARS), FC-BGA, FCP-CSP Inspection equipment (POSEIDON-S), Scale Sorter Of FC-BGA Products (8800 FI), Bump Metal Mask Inspection equipment (8800 MI), PCB Appearance Inspection equipment (8800 AI) and Lead Tab Process/Inspection equipment(Hawk 7300).